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ABSTRACT OF THE DISCLOSURE

2 A semiconductor workpiece holder used in electroplating systems
3 for plating metal layers onto a semiconductor workpieces, and is of
4 particular advantage in connection with plating copper onto
5 semiconductor materials. The workpiece holder includes electrode
6 assemblies which have a contact part which connects to a distal end of
7 an electrode shaft and bears against the workpiece and conducts current
8 therebetween. The contact part is preferably made from a corrosion
9 resistant material, such as platinum. The electrode assembly also
10 preferably includes a dielectric layer which covers the distal end of the
11 electrode shaft and seals against the contact part to prevent plating
12 liquid from corroding the joint between these parts.